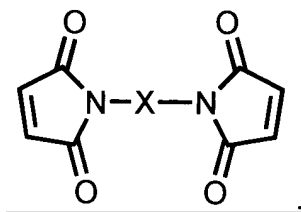


LISTING OF THE CLAIMS

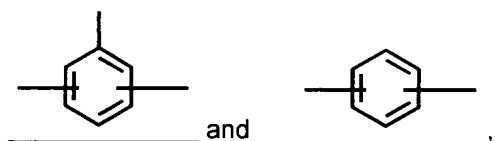
CLAIM 1	currently amended
CLAIM 2	original
CLAIM 3	canceled
CLAIM 4	canceled
CLAIM 5	canceled
CLAIM 6	previously amended
CLAIM 7	previously amended
CLAIM 8	original

TEXT OF CLAIMS CURRENTLY UNDER EXAMINATION

1. (CURRENTLY AMENDED) A method for improving the cohesive strength of a cured die attach adhesive at elevated temperature in which the die attach adhesive formulation comprises a liquid curable resin or a combination of curable resins, initiator, and filler, comprising adding to the uncured die attach adhesive formulation at ambient temperature an aromatic bismaleimide resin powder having a structure:



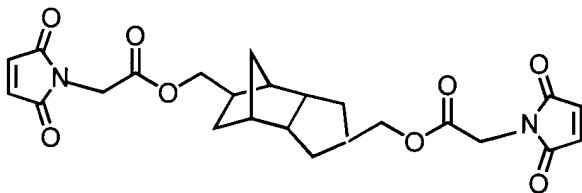
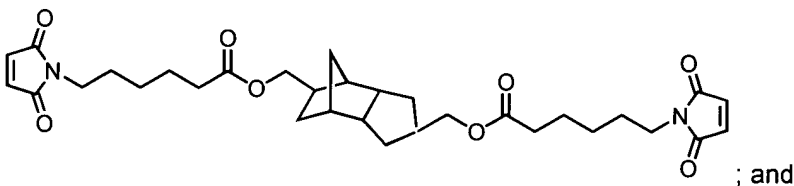
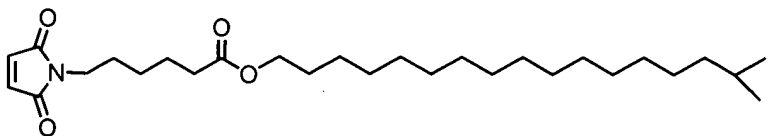
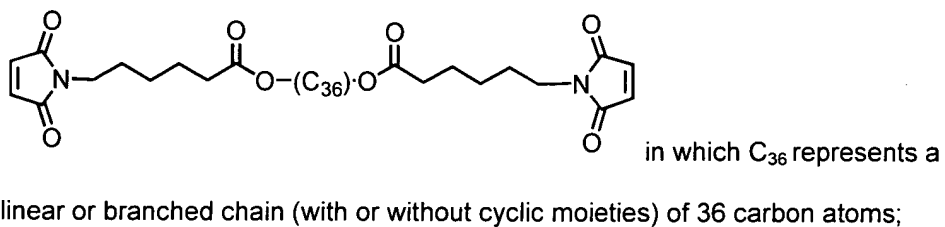
~~that~~ in which X is selected from the group consisting of



which bismaleimide resin powder does not dissolve in the liquid curable resin ~~such~~ so that the die attach adhesive formulation remains as a multi-phase system both before and after cure, and in which adhesive formulation the weight ratio of bismaleimide resin powder to liquid curable resin is ~~1:2-7~~ 1.6 to 1:45.

2. (ORIGINAL) The method according to claim 1 in which the elevated temperature is 260°C or less.

3. (CANCELED)
4. (CANCELED)
5. (CANCELED)
6. (PREVIOUSLY AMENDED) The method according to claim 1 in which the liquid curable resin is a maleimide resin, a cyanate ester resin, an acrylate resin, or a combination of those resins.
7. (PREVIOUSLY AMENDED) The method according to claim 6 in which the liquid curable resin is a maleimide resin selected from the group consisting of



8. (ORIGINAL) The method according to claim 6 in which the acrylate resin is selected from the group consisting of isobornyl acrylate, isobornyl methacrylate, lauryl acrylate, lauryl methacrylate, poly(butadiene) with acrylate functionality and poly(butadiene) with methacrylate functionality.